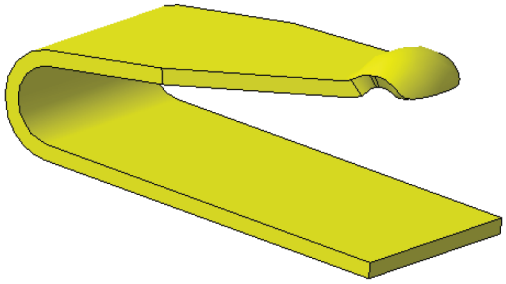
C-Clip Connector

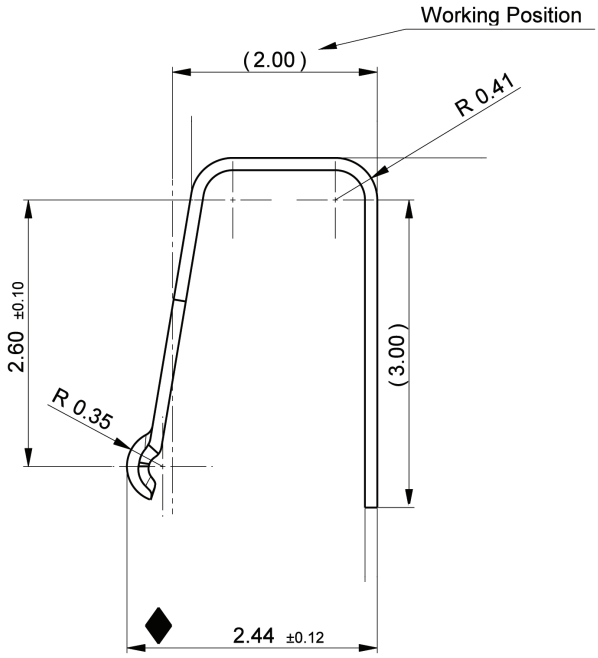
Pulse Part Number W9909

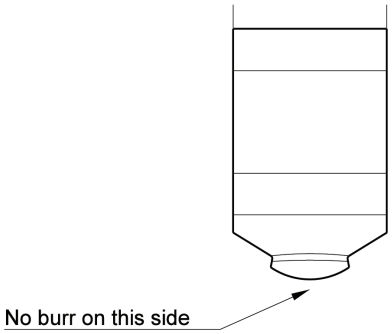


Ideal for board-to-antenna applications
Spring contact for positive connection
Surface mount technology; solder reflowable

Features
- PWB Footprint 3.2 x 1.7 mm
- Tape & Reel Packaging
- RoHS Compliant Product

Applications
- Antenna Contacts
- W3530 Antenna RF Contacts





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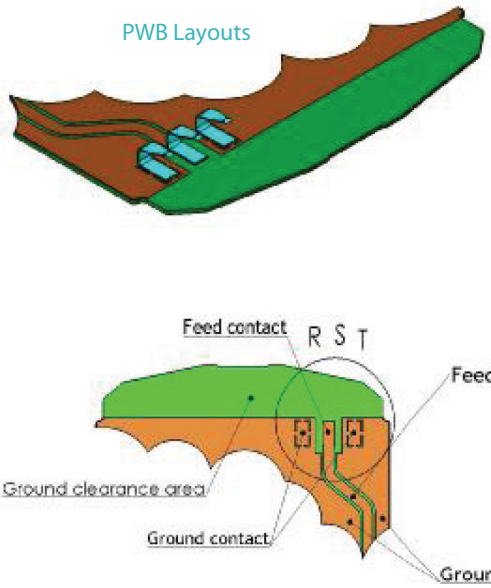
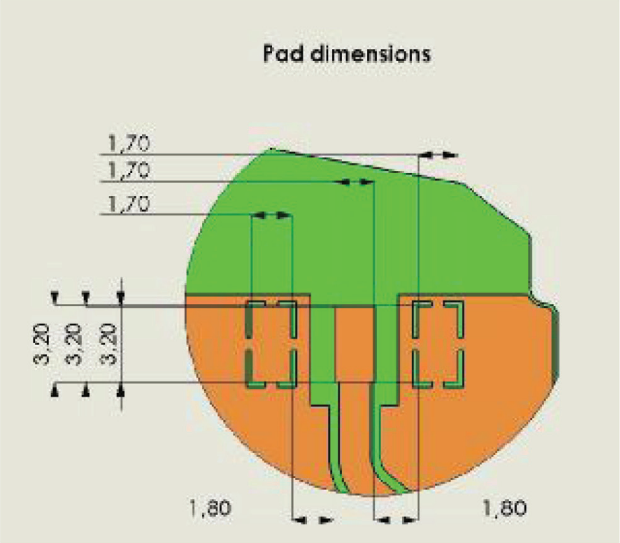
W9909 C-Clip Configuration and Dimensions

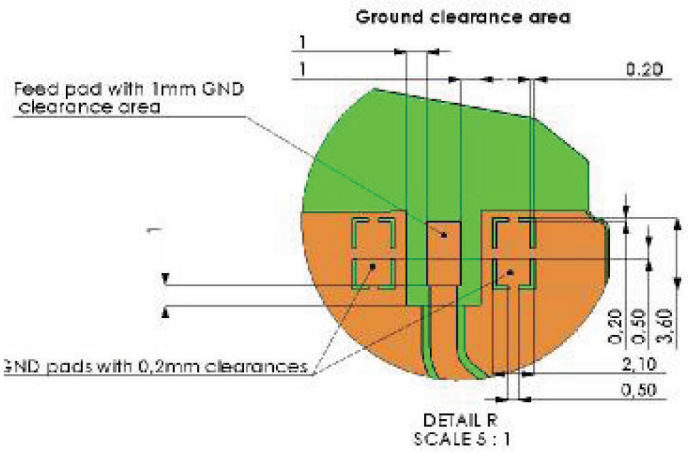
PWB Layouts



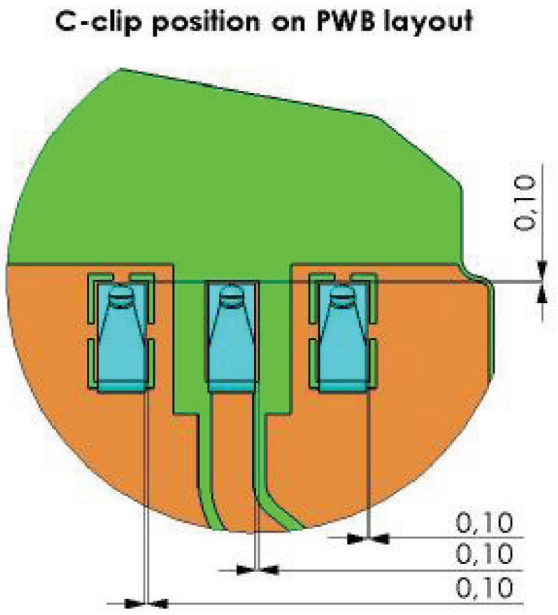
PWB Pad Dimensions and C-Clip Position for W9909



Ground Clearance Area for W9909 C-Clip



C-clip position on PWB layout



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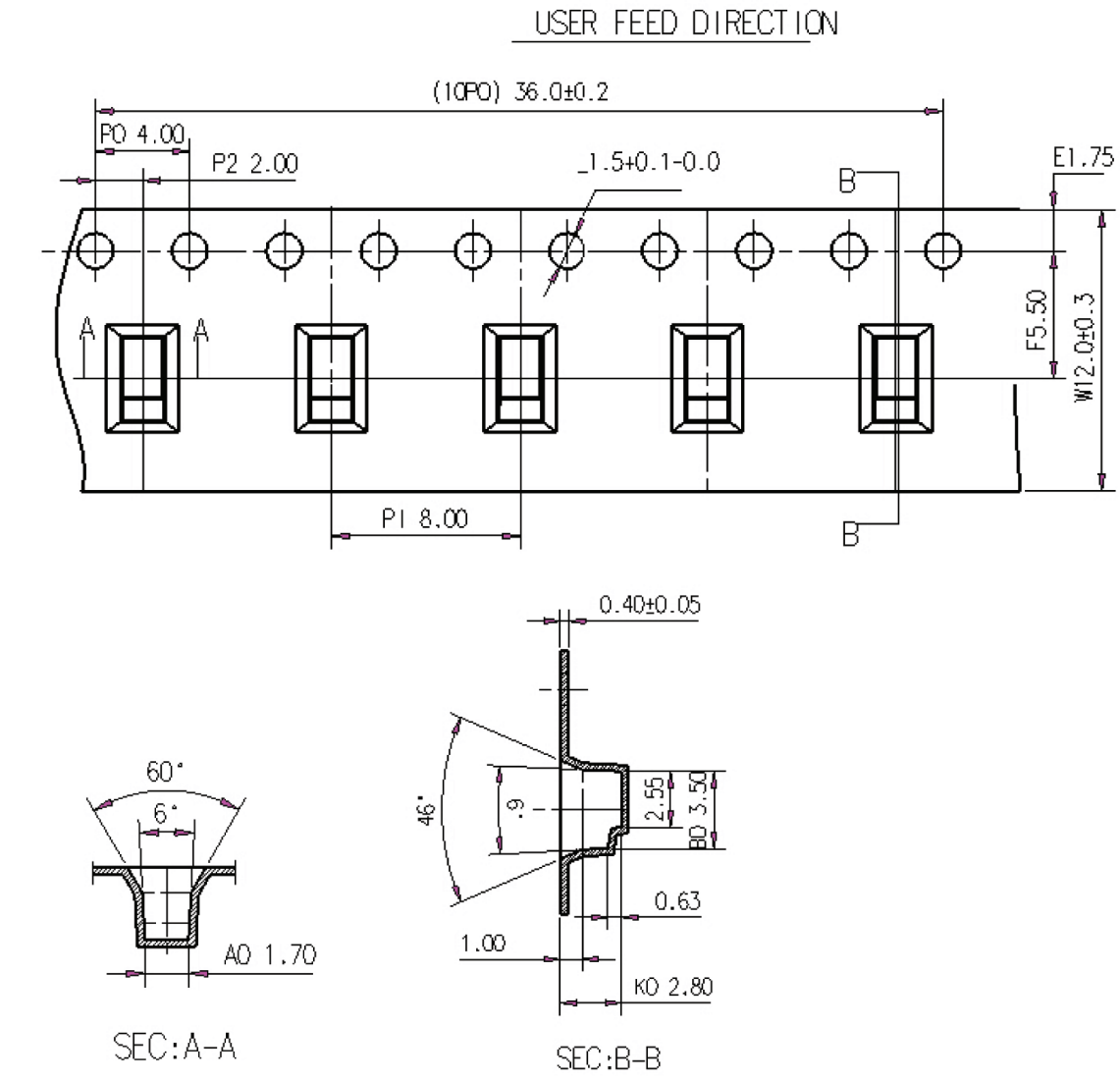
Reel packing is used for the C-clip.



NOTE:
1. MATERIAL:PS Clear-Thickness:0.40±0.05mm
2. Packing Length Per 22" Reel: 60 Meters
3. Component Load Per 13" Reel: 5000 Pcs
4. 10 SPROCKET HOLE CUMULATTIVE TOLERANCE: ±0.2
5. CARRIER CAMBER IS WITHIN 1mm IN 100mm

Figure 2. Connector packing.

C-Clip Connector

Pulse Part Number W9909

W9909 Connector Soldering

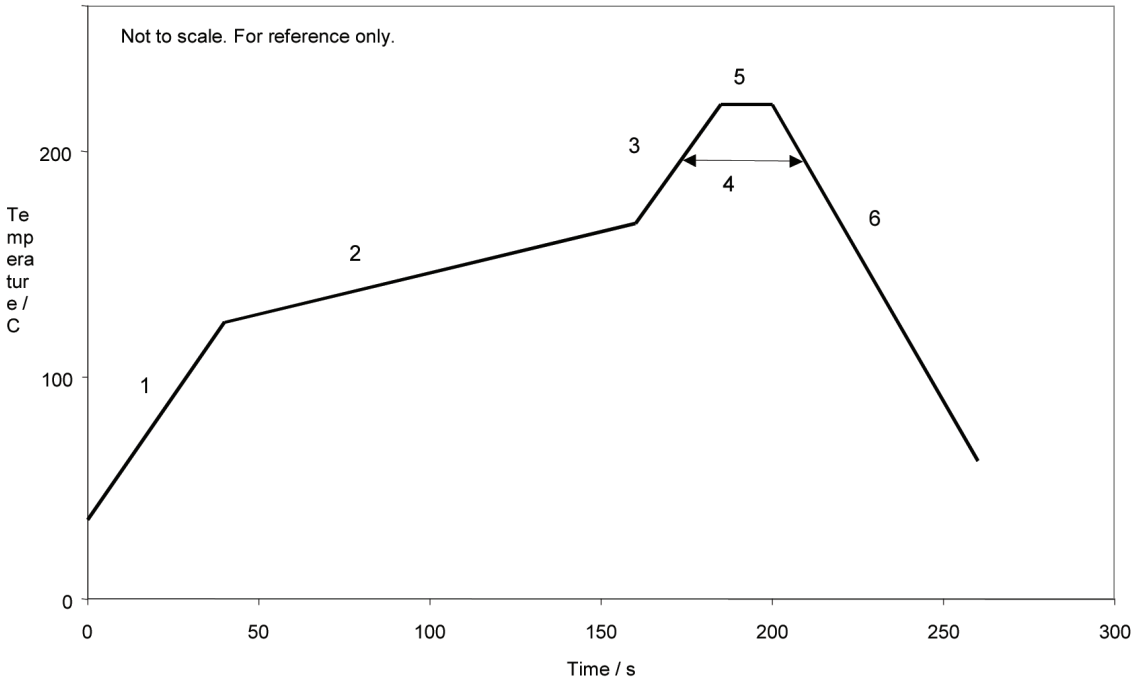
Recommendation for reflow soldering process

Printing stencil thickness 0.15 to 0.25 mm is recommended for the solder paste. The maximum soldering temperature should not exceed 260°C.

The temperature profile recommendations for reflow solder process are presented in Figure 1 and 2. The reflow profile presented in Figure 2 describes maximum reflow temperatures.

Figure 1 - Minimum temperature profile recommendation for reflow soldering process

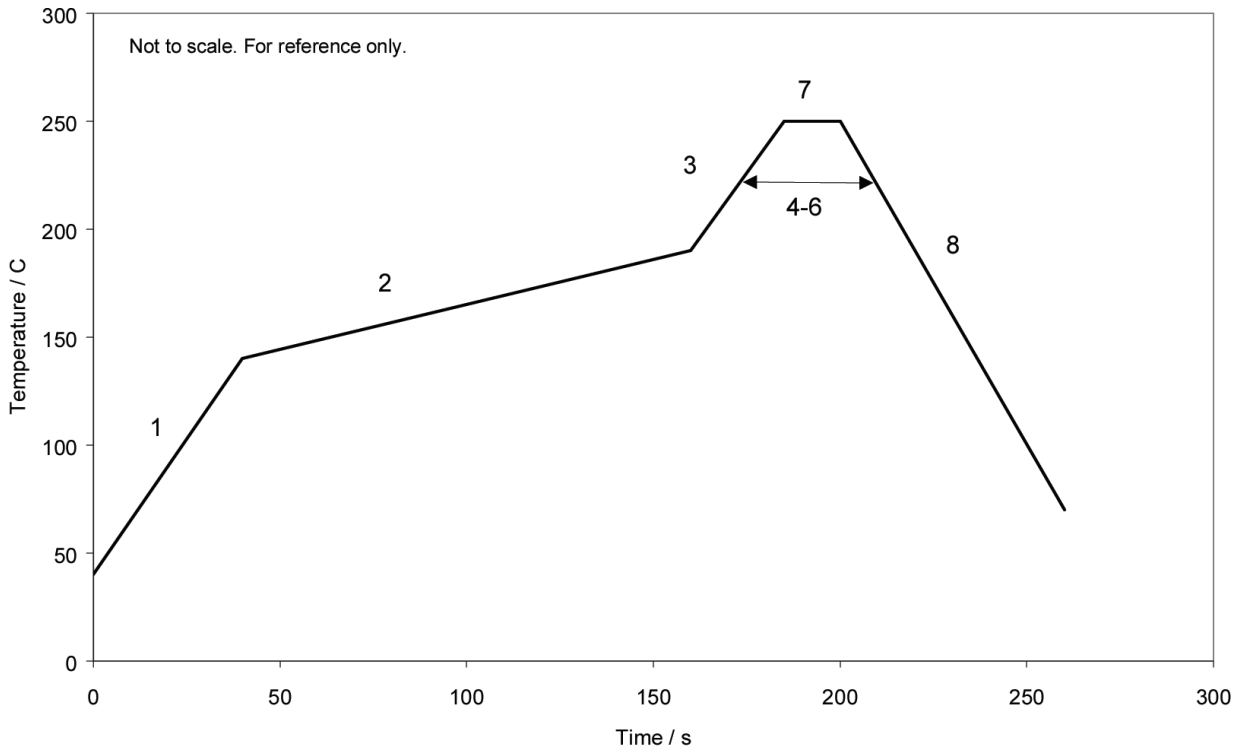
	Method of heat transfer	Controlled hot air convection
1	Average temperature gradient in preheating	2.5°C/s
2	Soak time	2-3 minutes
3	Max temperature gradient in reflow	3°C/s
4	Time above 217°C	Max 30 sec
5	Peak temperature in reflow	230°C for 10 seconds
6	Temperature gradient in cooling	Max -5°C/s



Pulse Part Number W9909

Figure 2 - Maximum temperature profile recommendation for reflow soldering process

	Method of heat transfer	Controlled hot air convection
1	Average temperature gradient in preheating	2.5°C/s
2	Soak time	2-3 minutes
3	Max temperature gradient in reflow	3°C/s
4	Time above 217°C	Max 60 sec
5	Time above 230°C	Max 50 sec
6	Time above 250°C	Max 10 sec
7	Peak temperature in reflow	260°C for 5 seconds
8	Temperature gradient in cooling	Max -5°C/s



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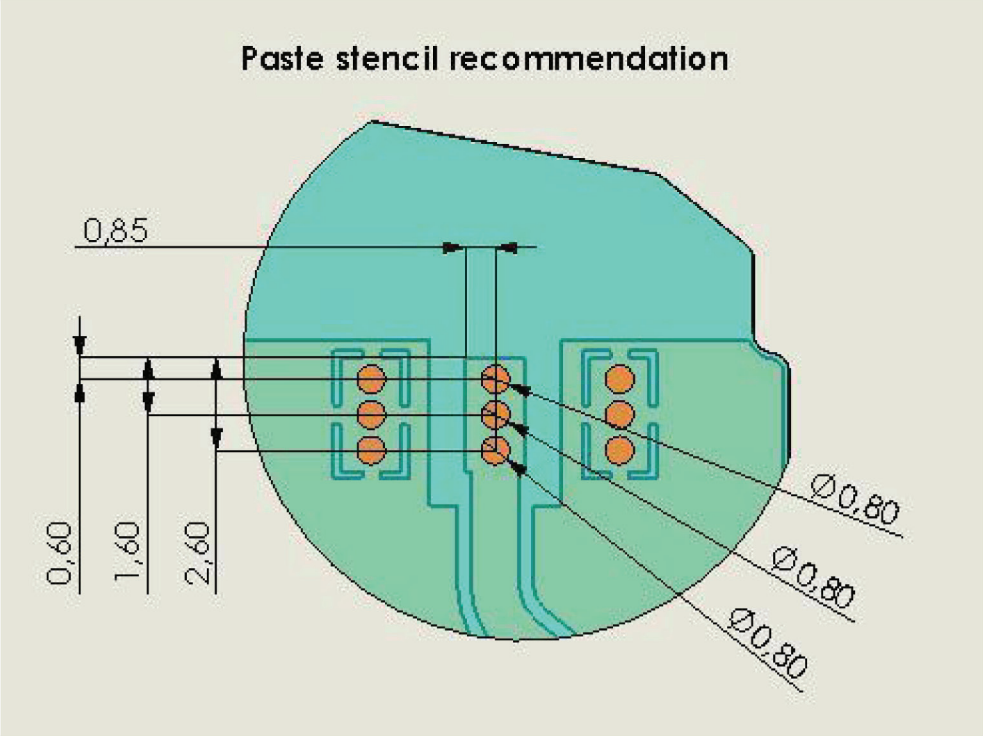
SMT notes



Pick & Place area